

WHAT IS CLAIMED:

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A1
✓ 1. A method of forming a thin film comprising the step of:
forming an AgPd alloy thin film using a sputtering target
material, wherein the AgPd alloy thin film comprises Pd in an
amount ranging from 0.5 to 4.9 atomic %.

✓ 2. The method of claim 1 wherein the alloy further comprises
at least one of Cu or Cr in an amount ranging from 0.1 to 3.5
atomic %.

3. A thin film comprising:
an AgPd alloy comprising Pd in an amount ranging from 0.5 to
4.9 atomic %.

4. The thin film of claim 3 further comprising at least one
of Cu or Cr in an amount ranging from 0.1 to 3.5 atomic %.

5. An optical recording medium comprising:
a thin film formed by using an AgPd alloy comprising Pd in an
amount ranging from 0.5 to 4.9 atomic %.

6. The optical recording medium of claim 5 wherein the AgPd
alloy further comprises at least one of Cu or Cr in an amount
ranging from 0.1 to 3.5 atomic %.

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A2

✓ 7. A method of forming a thin film comprising the step of:
forming an AgPdTi alloy thin film using a sputtering target material wherein the AgPdTi alloy comprises Pd in an amount ranging from 0.1 to 1.5 atomic % and Ti in an amount ranging from 0.1 to 2.9 atomic %.

8. A thin film comprising:
an AgPdTi alloy comprising Pd in an amount ranging from 0.1 to 1.5 atomic % and Ti in an amount ranging from 0.1 to 2.9 atomic %.

9. An optical recording medium comprising:
a thin film comprising an AgPdTi alloy comprising Pd in an amount ranging from 0.1 to 1.5 atomic % and Ti in an amount ranging from 0.1 to 2.9 atomic %.

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A3 }
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C1 }